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Speech subject:

Speech leader: Farhang Yazdani—CEO, BroadPak Corporation

Introduction of Speaker:

Farhang Yazdani is the President and CEO of BroadPak Corporation, a provider of advanced 2.5D/3D heterogeneous chiplet integration and co-packaged optics design/manufacturing services based in San Jose, California. Through his 23 years in the industry, he has served in various technical, management, and advisory positions with leading semiconductor companies worldwide. He is the author of the book “Foundations of Heterogeneous Integration: An Industry-Based, 2.5D/3D Pathfinding and Co-Design Approach”. He is the recipient of the 2013 NIPSIA award in recognition of his contribution to the advancement and innovations in packaging technologies. He has numerous publications and IPs in the area of 2.5D/3D Packaging and Assembly, serves on various technical committees, and is a frequent reviewer for the IEEE Journal of Advanced Packaging. He received his undergraduate and graduate degrees in Chemical Engineering and Mechanical Engineering from the University of Washington, Seattle.